

REGULATORY COMPLIANCE











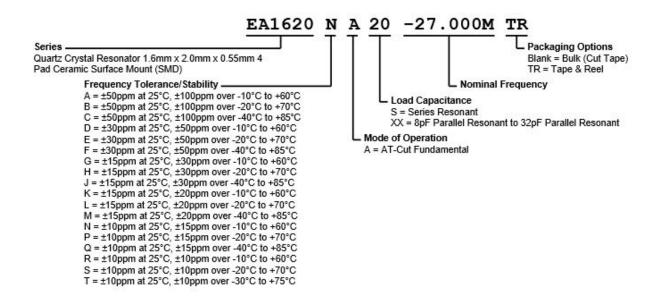
ITEM DESCRIPTION

Quartz Crystal Resonator 1.6mm x 2.0mm x 0.55mm 4 Pad Ceramic Surface Mount (SMD)

ELECTRICAL SPECIFICATIONS		
Nominal Frequency	16MHz to 54MHz	
Frequency Tolerance/Stability	±50ppm at 25°C, ±100ppm over -10°C to +60°C ±50ppm at 25°C, ±100ppm over -20°C to +70°C ±50ppm at 25°C, ±50ppm over -40°C to +85°C ±30ppm at 25°C, ±50ppm over -20°C to +70°C ±30ppm at 25°C, ±50ppm over -40°C to +85°C ±30ppm at 25°C, ±50ppm over -40°C to +85°C ±15ppm at 25°C, ±30ppm over -10°C to +60°C ±15ppm at 25°C, ±30ppm over -20°C to +70°C ±15ppm at 25°C, ±30ppm over -40°C to +85°C ±15ppm at 25°C, ±20ppm over -40°C to +85°C ±15ppm at 25°C, ±20ppm over -10°C to +60°C ±15ppm at 25°C, ±20ppm over -20°C to +70°C ±15ppm at 25°C, ±15ppm over -40°C to +85°C ±10ppm at 25°C, ±15ppm over -40°C to +85°C ±10ppm at 25°C, ±15ppm over -20°C to +70°C ±10ppm at 25°C, ±15ppm over -40°C to +85°C ±10ppm at 25°C, ±10ppm over -40°C to +70°C ±10ppm at 25°C, ±10ppm over -30°C to +70°C ±10ppm at 25°C, ±10ppm over -30°C to +70°C	
Aging at 25°C	±3ppm/year Maximum	
Load Capacitance	Series Resonant, 8pF Parallel Resonant to 32pF Parallel Resonant	
Shunt Capacitance	5pF Maximum	
Equivalent Series Resistance	160 Ohms Maximum over Nominal Frequency of 16MHz to 17.999999MHz 150 Ohms Maximum over Nominal Frequency of 18MHz to 19.999999MHz 120 Ohms Maximum over Nominal Frequency of 20MHz to 25.999999MHz 100 Ohms Maximum over Nominal Frequency of 26MHz to 29.999999MHz 80 Ohms Maximum over Nominal Frequency of 30MHz to 35.999999MHz 60 Ohms Maximum over Nominal Frequency of 36MHz to 54MHz	
Mode of Operation	AT-Cut Fundamental	
Drive Level	100μWatts Maximum	
Spurious Response	Measured from Fo to Fo +5000ppm -3dB Minimum	
Storage Temperature Range	-40°C to +125°C	
Insulation Resistance	Measured at 100Vdc 500 Megaohms Minimum	

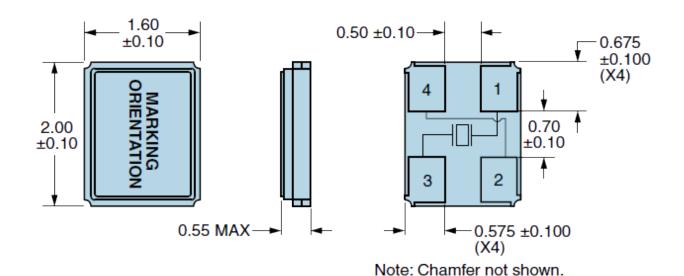


PART NUMBERING GUIDE





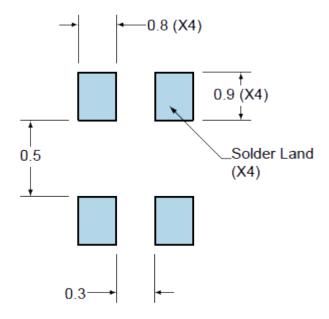
MECHANICAL DIMENSIONS



Seam Sealed

Terminal Plating Thickness: Gold (0.3 to 1.0µm) over Nickel (1.27 to 8.89µm).

SUGGESTED SOLDER PAD LAYOUT



PIN	CONNECTION
1	Crystal
2	Cover/Ground
3	Crystal
4	Cover/Ground

All Tolerances are ±0.1

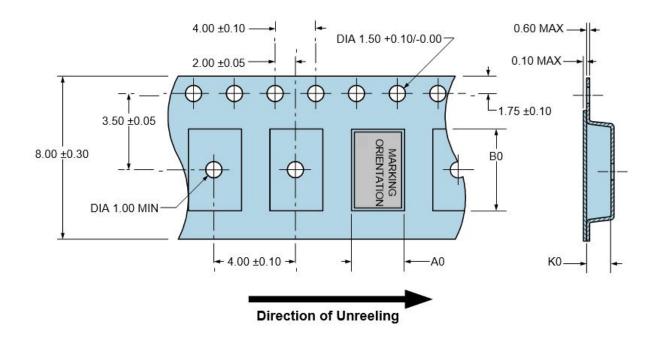
All Dimensions in Millimeters

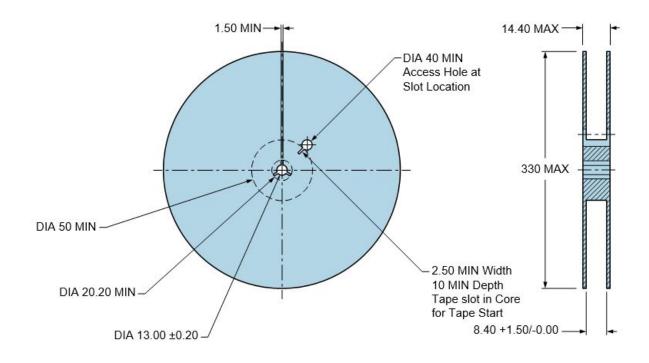


TAPE & REEL DIMENSIONS

Quantity per Reel: 1,000 Units

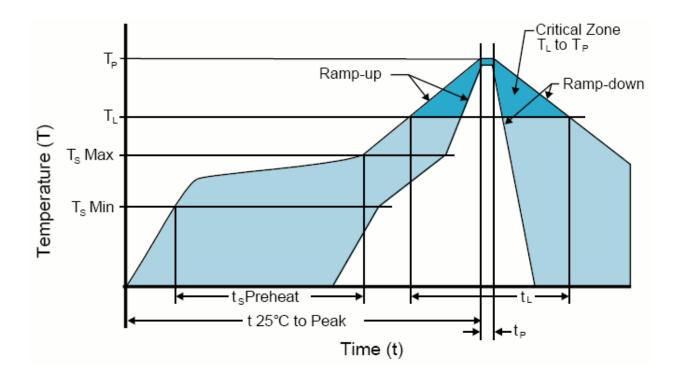
All Dimensions in Millimeters
Compliant to EIA-481







RECOMMENDED SOLDER REFLOW METHOD



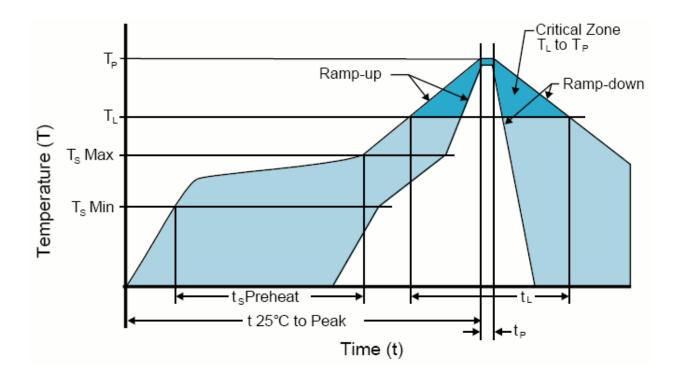
HIGH TEMPERATURE INFRARED/CONVECTION		
T _s MAX to T _L (Ramp-up Rate)	3°C/Second Maximum	
Preheat		
- Temperature Minimum (T _S MIN)	150°C	
- Temperature Typical (T _s TYP)	175°C	
- Temperature Maximum(T _s MAX)	200°C	
- Time (t _s)	60 - 180 Seconds	
Ramp-up Rate (T _L to T _P)	3°C/Second Maximum	
Time Maintained Above:		
- Temperature (T _L)	217°C	
- Time (t _L)	60 - 150 Seconds	
Peak Temperature (T _P)	260°C Maximum for 10 Seconds Maximum	
Target Peak Temperature(T _P Target)	250°C +0/-5°C	
Time within 5°C of actual peak (t _p)	20 - 40 Seconds	
Ramp-down Rate	6°C/Second Maximum	
Time 25°C to Peak Temperature (t)	8 Minutes Maximum	
Moisture Sensitivity Level	Level 1	
Additional Notes	Temperatures shown are applied to body of device.	

High Temperature Manual Soldering

260°C Maximum for 5 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)



RECOMMENDED SOLDER REFLOW METHOD



LOW TEMPERATURE INFRARED/CONVECTION		
T _s MAX to T _L (Ramp-up Rate)	5°C/Second Maximum	
Preheat		
- Temperature Minimum (T _s MIN)	N/A	
- Temperature Typical (T _s TYP)	150°C	
- Temperature Maximum(T _s MAX)	N/A	
- Time (t _s)	30 - 60 Seconds	
Ramp-up Rate (T _L to T _P)	5°C/Second Maximum	
Time Maintained Above:		
- Temperature (T _L)	150°C	
- Time (t _L)	200 Seconds Maximum	
Peak Temperature (T _P)	245°C Maximum	
Target Peak Temperature (T _P Target)	245°C Maximum 2 Times / 230°C Maximum 1 Time	
Time within 5°C of actual peak (tp)	10 Seconds Maximum 2 Times / 80 Seconds Maximum 1 Time	
Ramp-down Rate	5°C/Second Maximum	
Time 25°C to Peak Temperature (t)	N/A	
Moisture Sensitivity Level	Level 1	
Additional Notes	Temperatures shown are applied to body of device.	

Low Temperature Manual Soldering

185°C Maximum for 10 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)